MOSFETs Silicon N-channel MOS (U-MOSⅧ-H)

SSM3K361TU

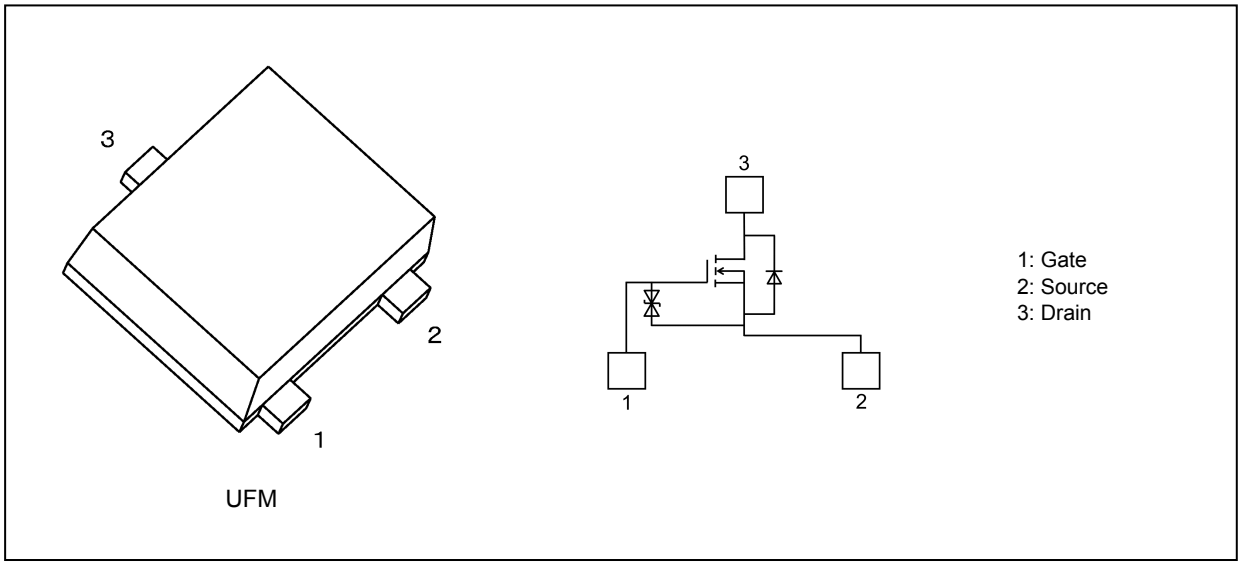
1. Applications

- Power Management Switches
- DC-DC Converters

2. Features

(1) AEC-Q101 qualified
(2) 175 ℃ MOSFET
(3) 4.5 V drive
(4) Low drain-source on-resistance
: $R_{DS(ON)}$ = 65 mΩ (typ.) (@V_{GS} = 4.5 V)
$R_{DS(ON)}$ = 51 mΩ (typ.) (@V_{GS} = 10 V)

3. Packaging and Pin Assignment



Start of commercial production
2016-12

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4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	100	V
Gate-source voltage			V_{GSS}	±20	
Drain current (DC)		(Note 1)	I_D	3.5	A
Drain current (pulsed)		(Note 1), (Note 2)	I_{DP}	14	
Power dissipation		(Note 3)	P_D	1.0	W
Power dissipation	(t = 10 s)	(Note 3)	P_D	1.8	
Single-pulse avalanche energy		(Note 4)	E_{AS}	9.1	mJ
Avalanche current			I_{AR}	3.5	A
Channel temperature		(Note 5)	T_{ch}	175	°C
Storage temperature		(Note 5)	T_{stg}	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed 175 °C.

Note 2: Pulse width ≤ 10 ms, Duty ≤ 1 %

Note 3: Device mounted on a 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm^2)

Note 4: V_{DD} = 25 V, T_{ch} = 25 °C (Initial state), L = 1 mH, R_G = 25 Ω

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, $R_{th(ch-a)}$, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

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5. Electrical Characteristics

5.1. Static Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{DS} = 0 V, V_{GS} = ±16 V	—	—	±10	μA
Drain cut-off current		I_{DSS}	V_{DS} = 100 V, V_{GS} = 0 V	—	—	10	
Drain-source breakdown voltage		$V_{(BR)DSS}$	I_D = 10 mA, V_{GS} = 0 V	100	—	—	V
Drain-source breakdown voltage	(Note 1)	$V_{(BR)DSX}$	I_D = 10 mA, V_{GS} = -20 V	80	—	—	
Gate threshold voltage	(Note 2)	V_{th}	V_{DS} = 10 V, I_D = 0.1 mA	1.5	—	2.5	V
Drain-source on-resistance	(Note 3)	$R_{DS(ON)}$	I_D = 1 A, V_{GS} = 4.5 V	—	65	92	mΩ
			I_D = 2 A, V_{GS} = 10 V	—	51	69	

Note 1: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (0.1 mA for this device). Then, for normal switching operation, $V_{GS(ON)}$ must be higher than V_{th}, and $V_{GS(OFF)}$ must be lower than V_{th}. This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$.
Take this into consideration when using the device.

Note 3: Pulse measurement.

5.2. Dynamic Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	—	430	—	pF
Reverse transfer capacitance	C_{rss}		—	22	—	
Output capacitance	C_{oss}		—	160	—	
Switching time (rise time)	t_r	V_{DD} = 30 V, I_D = 1.0 A, V_{GS} = 0 to 4.5 V, R_G = 50 Ω Duty ≤ 1 %,Input: t_r, t_f < 5 ns, Common source, See Chapter 5.3.	—	9	—	ns
Switching time (turn-on time)	t_{on}		—	21	—	
Switching time (fall time)	t_f		—	7	—	
Switching time (turn-off time)	t_{off}		—	16	—	

5.3. Switching Time Test Circuit

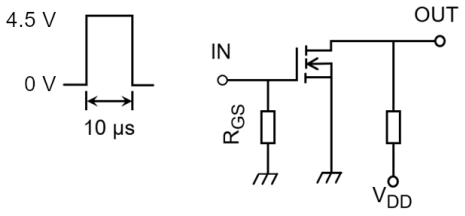


Fig. 5.3.1 Switching Time Test Circuit

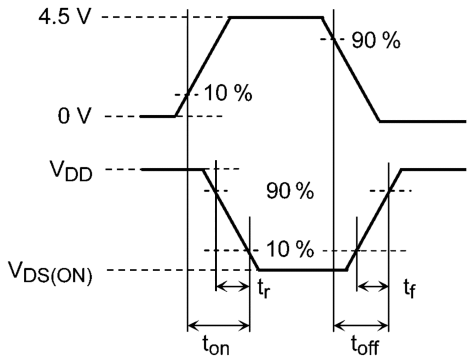


Fig. 5.3.2 Input Waveform/Output Waveform

5.4. Gate Charge Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	V_{DD} = 50 V, I_D = 2.0 A, V_{GS} = 4.5 V	—	3.2	—	nC
Gate-source charge 1	Q_{gs1}		—	1.1	—	
Gate-drain charge	Q_{gd}		—	1.5	—	

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5.5. Source-Drain Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Diode forward voltage	(Note 1)	V_{DSF}	I_D = -3.5 A, V_{GS} = 0 V	—	-0.9	-1.5	V

Note 1: Pulse measurement.

6. Marking

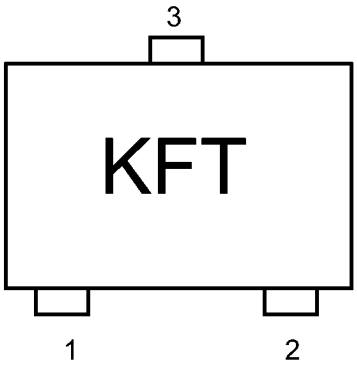


Fig. 6.1 Marking

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7. Characteristics Curves (Note)

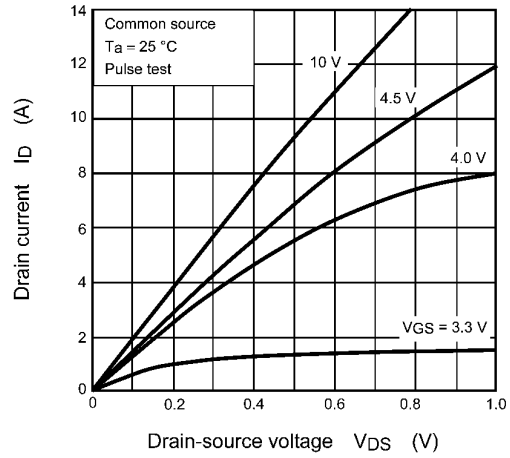


Fig. 7.1 I_D - V_{DS}

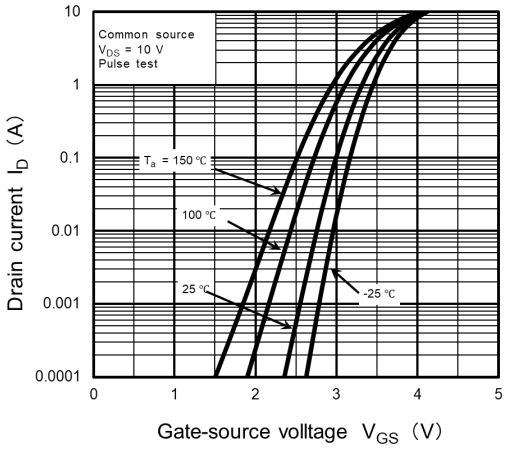


Fig. 7.2 I_D - V_{GS}

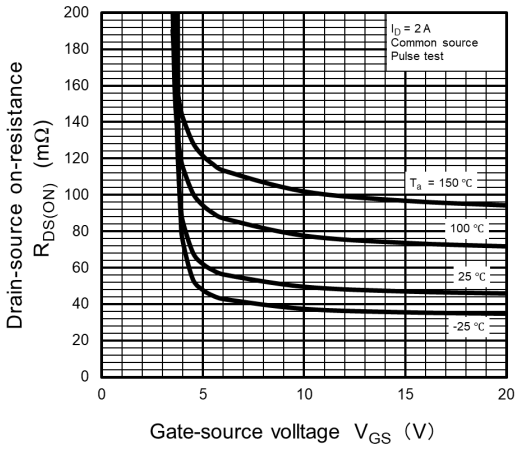


Fig. 7.3 $R_{DS(ON)}$ - V_{GS}

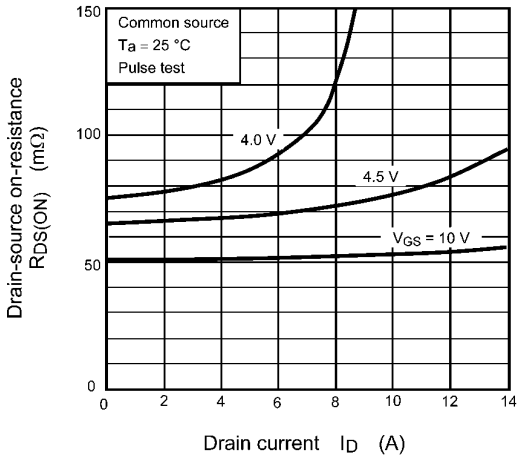


Fig. 7.4 $R_{DS(ON)}$ - I_D

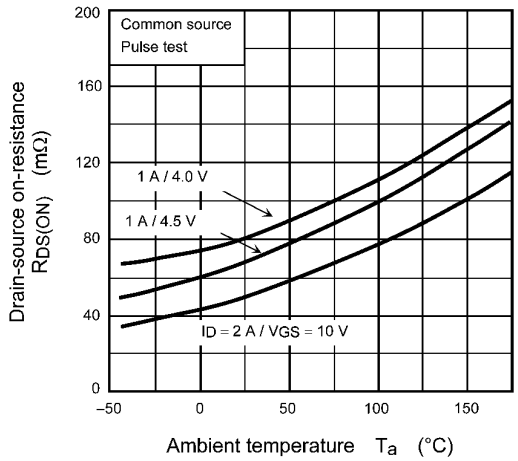


Fig. 7.5 $R_{DS(ON)}$ - T_a

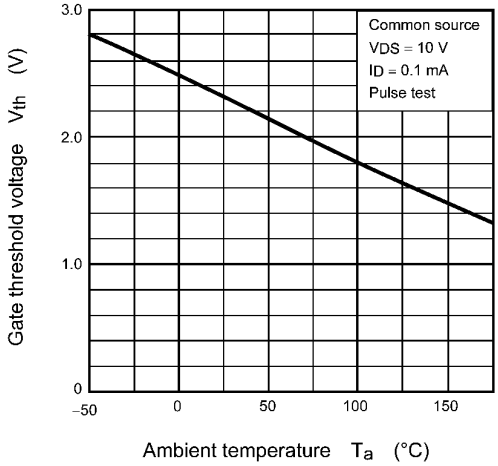


Fig. 7.6 V_{th} - T_a

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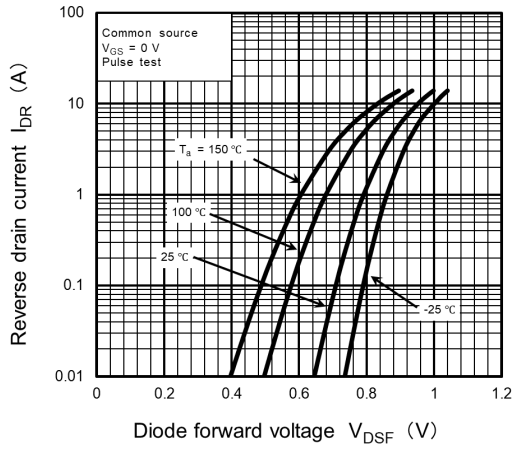


Fig. 7.7 I_{DR} - V_{DS}

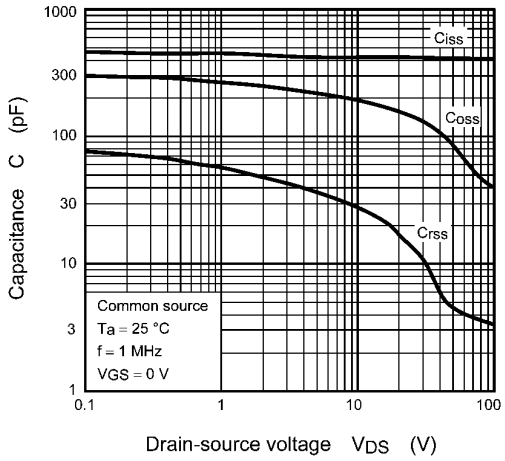


Fig. 7.8 C - V_{DS}

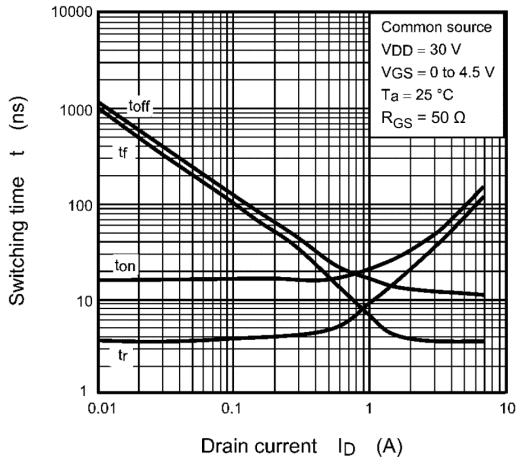


Fig. 7.9 t - I_D

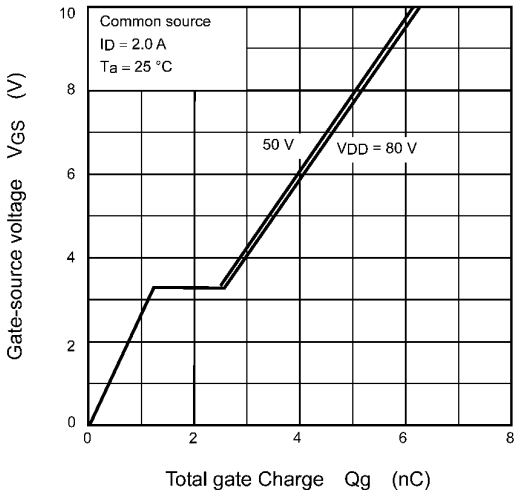


Fig. 7.10 Dynamic Input Characteristics

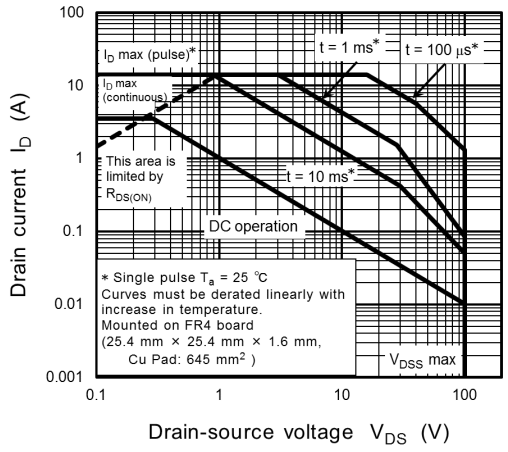


Fig. 7.11 Safe Operating Area

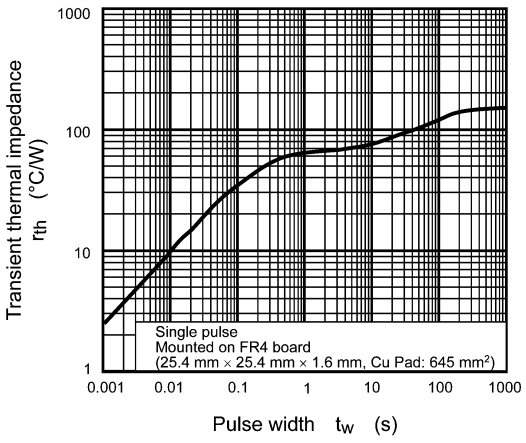


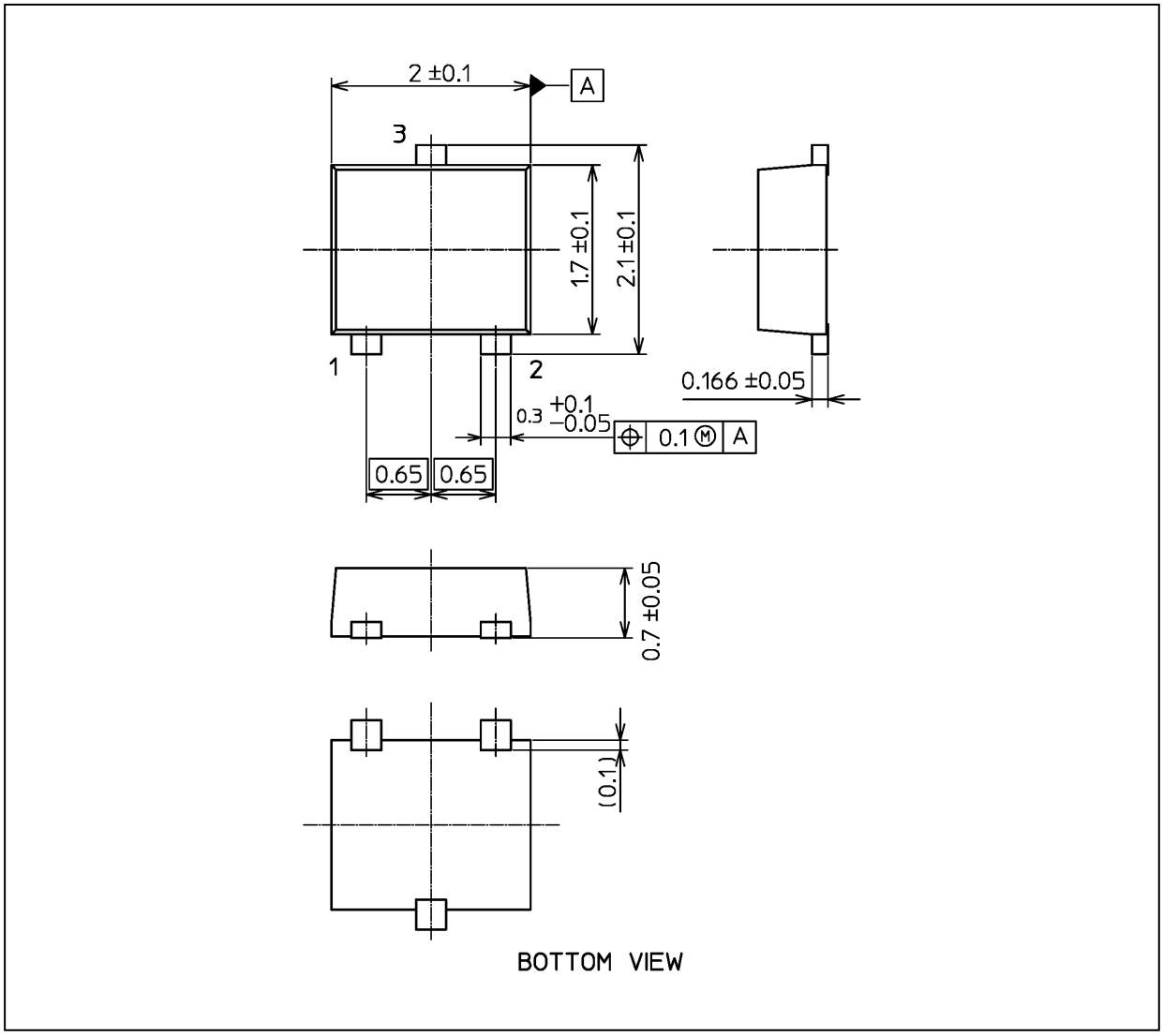
Fig. 7.12 r_{th} - t_w

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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Package Dimensions

Unit: mm



Weight: 6.6 mg (typ.)

Package Name(s)
Nickname: UFM

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